



Product Change Notification

Change Notification #: 116960 - 00
Change Title: Intel® Server System R1208WFQYSR, Intel® Server System R2208WF0ZSR, PCN 116960-00, Product Design, Label, Firmware and Label Logo Update
Date of Publication: May 22, 2019

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	June 7, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on Intel® Server Systems R1208WFQYSR and R2208WF0ZSR:

1. Update BIOS revision to R02.01.0008
2. Update the Manageability Engine (ME) firmware revision to 04.01.04.251
3. Update the Baseboard Management Controller (BMC) firmware revision to 1.93.870cf4f0
4. Update the FRUSDR revision to 1.93

Intel is updating the system outer box stacking logo, original logo mean MAX 7-layers in total, however, only 6-layers as MAX can be supported by logistics racking limitation.

- System outer box stacking logo label images.

	Current	New
	Original outer box	New outer box
IPN	J33994-001	J33994-002
Description	System outer box with J33994-001 IPN and 6 layers stacking logo printing	Updated system outer box with J33994-002 IPN and 5 layers stacking logo printing
Photos	<p>Diagram showing current system outer box label with dimensions: 2X 25, 25, 13 to 25. Part numbers: ID: 970 X 564 X 234 MM, OD: 983 X 577 X 260 MM, P/N: J33994-001, XX-XX-XX. Includes handling icons (upward arrows, fragile, no open flame, no rain).</p>	<p>Diagram showing new system outer box label with dimensions: 2X 25, 13 to 25. Part numbers: ID: 970 X 564 X 234 MM, OD: 983 X 577 X 260 MM, P/N: J33994-002, XX-XX-XX. Includes handling icons (upward arrows, fragile, no open flame, no rain).</p>

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
R2208WF0ZSR	986050	K39997-001	H87179-871 H87178-881	K39997-002	H87178-872 H87178-882
R1208WFQYSR	986059	K40302-001	H87178-871 H87178-881	K40302-002	H87178-872 H87178-882

PCN Revision History:

Date of Revision:

May 22, 2019

Revision Number:

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Reason:

Originally Published PCN



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116960 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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